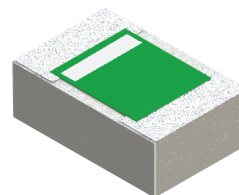


## RZ0805ZZ-XXXXJN-83 Features:

- Wraparound One Extended Pad Configuration
- Solder Attachment
- Customer Defined Testing Available
- RoHS Compliant or Sn62
- Tape & Reel or Waffle Pack Available (Standard is bulk)
- 5% Resistor Tolerance



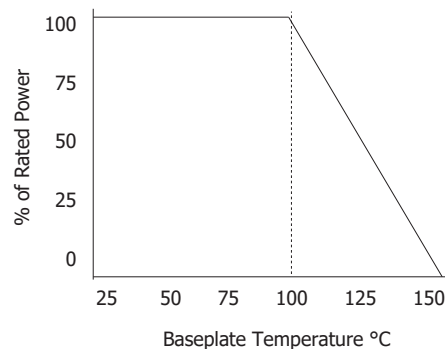
■ Actual Size

## RZ0805ZZ-XXXXJN-83 Parameters:

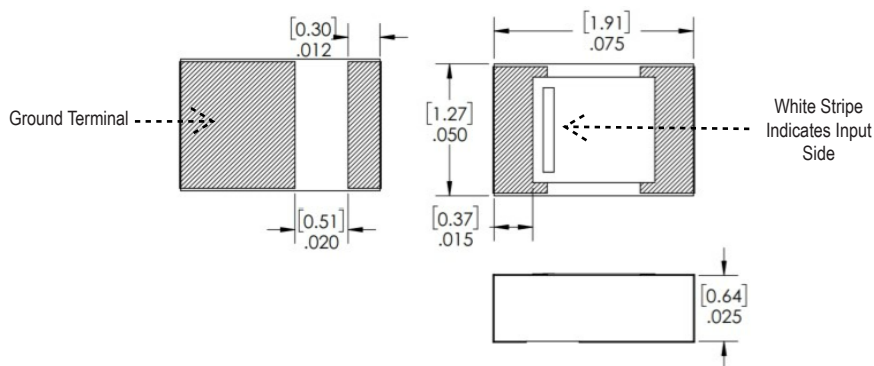
Resistance Range:	0.5Ω - 1MΩ	
Rated Power:	1.5W*	
Return Loss (Typical)**:	20dB or Better	(DC - 3GHz)
	17dB or Better	(>3GHz - 4GHz)
Construction:	Thick Film on BeO Free Ceramic	
Operating Temperature:	-55 to +150°C	

\* Rating based on ≤100°C constant baseplate temperature  
 \*\* Test performed on a 50Ω device in a matched, continuous 50Ω system with proper workmanship

## RZ0805ZZ-XXXXJN-83 Power Derating Curve



## RZ0805ZZ-XXXXJN-83 Dimensions:



Dimensions in inches [mm]  
 Tolerance is ± 0.005 [0.127]  
 unless otherwise stated

## Ordering Information:

RZ	0805	ZZ	-	XXXX	J	N	-	83	UU
Prefix for Wraparound Resistor w/ One Extended Backpad	Size 0805	Value Code 50R0 - 50Ω 1000 - 100Ω 1001 - 1KΩ 1002 - 10KΩ 1003 - 100KΩ 1004 - 1MΩ			Tolerance J - 5%	Normal Inspection Contact factory for additional options		Substrate 83 - 0.025" BeO Free Ceramic	Packaging Blank - Bulk TR - Tape and Reel WP - Waffle Pack
Terminal Metallization									
AS -	Tin Lead over Platinum Palladium Gold								
CB -	Tin Lead over Nickel over Silver								
CT -	100% Matte Tin over Nickel over Silver								
					RoHS	Magnetic	Solder	Epoxy	Wirebond
					No	No	Yes	No	No
					No	Yes	Yes	No	No
					Yes	Yes	Yes	No	No

Barry Industries reserves the right to change part number and/or process without notification.

**RZ0805ZZ-XXXXJN-83 Reliability Specifications:**

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65°C to +150°C 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

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